

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUNSOP HONG	10/21/2021
SEONGNAM OH	10/21/2021
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD.
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17508850
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	HEMAVATHY PERUMAL, REG. NO. 76,941
SIGNATURE:	/Hemavathy Perumal/
DATE SIGNED:	10/22/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 1	
source=Declaration-Assignment#page1.tif	

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET
(37 CFR 1.76) AND ASSIGNMENT**

Title of Invention	TWO-DIMENSIONAL (2D) FEATURE DATABASE GENERATION
As the undersigned inventor, I hereby declare that:	
This combined declaration and assignment is directed to:	<input checked="" type="checkbox"/> The attached application, or <input type="checkbox"/> United States application or PCT International application number _____ filed on _____.
The above-identified application was made or authorized to be made by me.	
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.	
I have reviewed and understand the contents of the application including the claims, for which this combined declaration and assignment is being submitted.	
I am aware of the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR 1.56.	
WHEREAS, <u>Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 129, Samsung-ro, Yeongtong-gu Suwon-si, Gyeonggi-do, Korea</u> (hereinafter referred to as "ASSIGNEE"), desires to acquire the entire right, title and interest in said invention and to any patent that may be granted thereon in the United States and foreign countries;	
NOW, THEREFORE, for good and valuable consideration, the receipt whereof is hereby acknowledged, We, the below named inventors, hereby sell, assign and transfer to said ASSIGNEE, its successors and assigns, the entire right, title and interest in the above-identified application and the invention disclosed therein in all countries, including all divisional applications, continuation applications, and corresponding priority applications including those to which priority is claimed under the International Convention of Paris including under 35 U.S.C. 119, substitutions, and renewals thereof, and to all patents that may be granted thereon, and all reissues thereof.	
We hereby authorize and request the Patent Office Officials in the United States and all foreign countries to issue patents, when granted, to said ASSIGNEE, its successors and assigns. Further, We agree that said ASSIGNEE, its successors and assigns, may apply for patents for the invention in foreign countries without further authorization from us. Also, We agree to execute all papers and generally to do everything possible to aid said ASSIGNEE, its successors and assigns, in obtaining and enforcing patents for the invention in all countries.	
I hereby acknowledge that any willful false statement made in this combined declaration and assignment is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.	

LEGAL NAME OF FIRST INVENTOR (e.g., full first name, middle initial, last name)

Inventor: Hunsop Hong Date: Oct 21, 2021

Signature: Hunsop Hong

LEGAL NAME OF SECOND INVENTOR (e.g., full first name, middle initial, last name)

Inventor: Seongnam Oh Date: Oct 21, 2021

Signature: *seongnam oh*